

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): William D. Boyd, et al.

Art Unit: Not Assigned

Serial No.: Not Assigned

Examiner: Not Assigned

Filed: Herewith

Docket: TI-37214

For: Wafer-Level Assembly Method for Chip-Size Devices Having Flipped Chips

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Karen Vertz 4-16-04
Karen Vertz Date

PRELIMINARY AMENDMENT

Dear Sir:

This application claims priority under 35 USC 119 (e)(1) of provisional application number 60/535,572, filed 01/08/04.

Please amend the specification by inserting before the first line the sentence:

—This application claims priority under 35 USC § 119 (e) (1) of provisional application number 60/535,572 filed 01/08/04.—

Should the Examiner have any further comments or suggestions, it is respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

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Respectfully submitted,

Yingsheng Tung
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